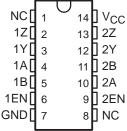
- Meets or Exceeds the Requirements of ANSI EIA/TIA-422-B and ITU Recommendation V.11
- Single 5-V Supply
- Balanced Line Operation
- TTL Compatible
- High-Impedance Output State for Party-Line Applications
- High-Current Active-Pullup Outputs
- Short-Circuit Protection
- Dual Channels
- Clamp Diodes at Inputs

D OR N PACKAGE (TOP VIEW)



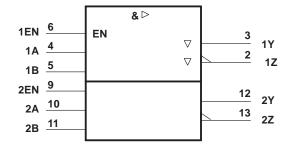
NC-No internal connection

description

The SN75159 dual differential line driver with 3-state outputs is designed to provide all the features of the SN75158 line driver with the added feature of driver output controls. There is an individual control for each driver. When the output control is low, the associated outputs are in a high-impedance state and the outputs can neither drive nor load the bus. This permits many devices to be connected together on the same transmission line for party-line applications.

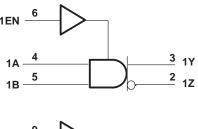
The SN75159 is characterized for operation from 0°C to 70°C.

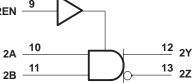
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



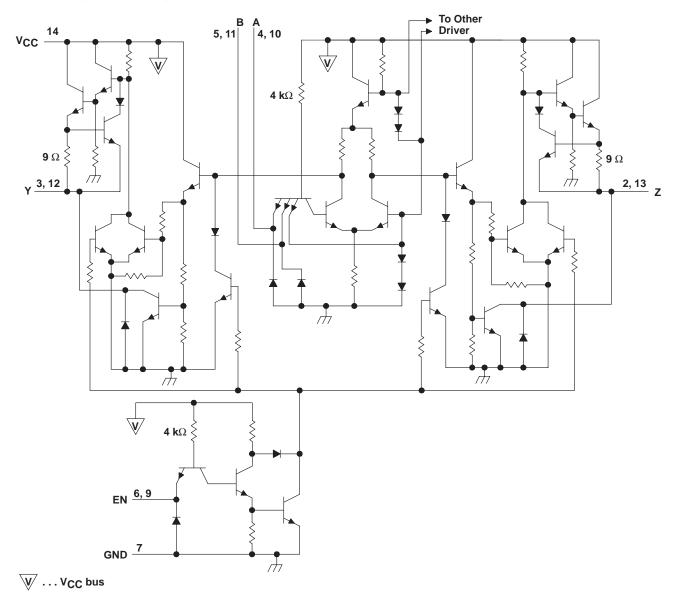




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



schematic (each driver)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Input voltage, V _I	
Off-state voltage applied to open-collector outputs	
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{Stq}	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
D	950 mW	7.6 mW/°C	608 mW		
N	1150 mW	9.2 mW/°C	736 mW		

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, V _{IL}			0.8	V
High-level output voltage, IOH			-40	mA
Low-level output current, I _{OL}			40	mA
Operating free-air temperature, T _A	0		70	°C



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values except differential output voltage VOD are with respect to the network ground terminal. VOD is at the Y output with respect to the Z output.

SN75159 **DUAL DIFFERENTIAL LINE DRIVER** WITH 3-STATE OUTPUTS

SLLS088B - JANUARY 1977 - REVISED MAY 1995

electrical characteristics over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	MIN	TYP [†]	MAX	UNIT		
VIK	Input clamp voltage	V _{CC} = 4.75 V,	$I_{I} = -12 \text{ mA}$			-0.9	-1.5	V
VOH	High-level output voltage	V _{CC} = 4.75 V, V _{IH} = 2 V,	$V_{IL} = 0.8 \text{ V},$ $I_{OH} = -40 \text{ mA}$		2.4	3		٧
VOL	Low-level output voltage	V _{CC} = 4.75 V, V _{IH} = 2 V,	V _{IL} = 0.8 V, I _{OL} = 40 mA			0.25	0.4	٧
Voк	Output clamp voltage	V _{CC} = 5.25 V,	$I_O = -40 \text{ mA}$			-1.1	-1.5	V
٧o	Output voltage	$V_{CC} = 4.75 \text{ V to } 5.25 \text{ V},$	IO = 0		0		6	V
V _{OD1}	Differential output voltage	$V_{CC} = 5.25 \text{ V},$	I _O = 0			3.5	^{2V} OD2	V
VOD2	Differential output voltage	V _{CC} = 4.75 V			2	3		V
∆IVODI	Change in magnitude of differential output voltage‡	V _{CC} = 4.75 V				±0.02	±0.4	٧
V	Common-mode output	V _{CC} = 5.25 V	R_L = 100 Ω, See Figure 1			1.8	3	V
Voc	voltage§	V _{CC} = 4.75 V				1.5	3	V
∆IVocI	Change in magnitude of common-mode output voltage‡	V _{CC} = 4.75 V to 5.25 V				±0.01	±0.4	٧
			V _O = 6 V			0.1	100	
I _O	Output current with power off	VCC = 0	$V_{O} = -0.25 \text{ V}$			-0.1	-100	μΑ
			$V_0 = -0.25 \text{ V}$	to 6 V			±100	
			T _A = 25°C	$V_O = 0$ to V_{CC}			±10	
	Off state (high image days a	V 505V		VO = 0			-20	
loz	Off-state (high-impedance state) output current	V _{CC} = 5.25 V, Output controls at 0.8 V	T _A = 70°C	V _O = 0.4 V			±20	μΑ
	, , , , , , , , , , , , , , , , , , , ,		14-700	V _O = 2.4 V	±		±20	
				AO = ACC			20	
H	Input current at maximum input voltage	V _{CC} = 5.25 V,	V _I = 5.5 V				1	mA
ΙΗ	High-level input current	V _{CC} = 5.25 V,	V _I = 2.4 V				40	μΑ
Ι _Ι L	Low-level input current	V _{CC} = 5.25 V,	V _I = 0.4 V			-1	-1.6	mA
Ios	Short-circuit output current¶	V _{CC} = 5.25 V			-40	-90	-150	mA
ICC	Supply current (both drivers)	V _{CC} = 5.25 V, T _A = 25°C,	Inputs grounde No load	ed,		47	65	mA

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C except for V_{OC}, for which V_{CC} is as stated under test conditions.



 $[\]pm \Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitudes of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low

[§] In ANSI Standard EIA/TIA-422-B, V_{OC}, which is the average of the two output voltages with respect to GND, is called output offset voltage, V_{OS}. ¶ Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.

switching characteristics over operating free-air temperature range, $V_{CC} = 5 \text{ V}$

	PARAMETER	TEST CONDITION	MIN	TYP [†]	MAX	UNIT	
^t PLH	Propagation delay time, low-to-high-level output	$C_L = 30 \text{ pF}, R_L = 100 \Omega,$	See Figure 2,		16	25	ns
tPHL	Propagation delay time, high-to-low-level output	Termination A			11	20	ns
^t PLH	Propagation delay time, low-to-high-level output	C _I = 15 pF, See Figure 2,	Tormination P		13	20	ns
tPHL	Propagation delay time, high-to-low-level output	CL = 15 pr, See rigule 2,	Termination B		9	15	ns
tTLH	Transition time, low-to-high-level output	$C_L = 30 \text{ pF}, R_L = 100 \Omega,$	See Figure 2,		4	20	ns
tTHL	Transition time, high-to-low-level output	Termination A			4	20	ns
^t PZH	Output enable time to high level	$C_L = 30 \text{ pF}, R_L = 180 \Omega,$	See Figure 3		7	20	ns
tPZL	Output enable time to low level	$C_L = 30 \text{ pF}, R_L = 250 \Omega,$	See Figure 4		14	40	ns
^t PHZ	Output disable time from high level	$C_L = 30 \text{ pF}, R_L = 180 \Omega,$	See Figure 3		10	30	ns
t _{PLZ}	Output disable time from low level	$C_L = 30 \text{ pF}, R_L = 250 \Omega,$	See Figure 4		17	35	ns
	Overshoot factor	$R_L = 100 \Omega$, See Figure 2,	Termination C			10%	

[†] All typical values are at T_A = 25°C.

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	EIA/TIA-422-B
VO	V _{oa} , V _{ob}
V _{OD1}	V _O
V _{OD2}	V _t
Δ V _{OD}	$ V_t - \overline{V}_t $
Voc	V _{os}
Δ VOC	$ V_{OS} - \overline{V}_{OS} $
los	I _{sa} , I _{sb}
0	I _{xa} , I _{xb}

PARAMETER MEASUREMENT INFORMATION

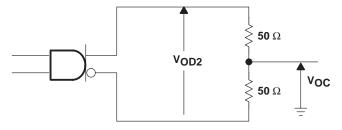
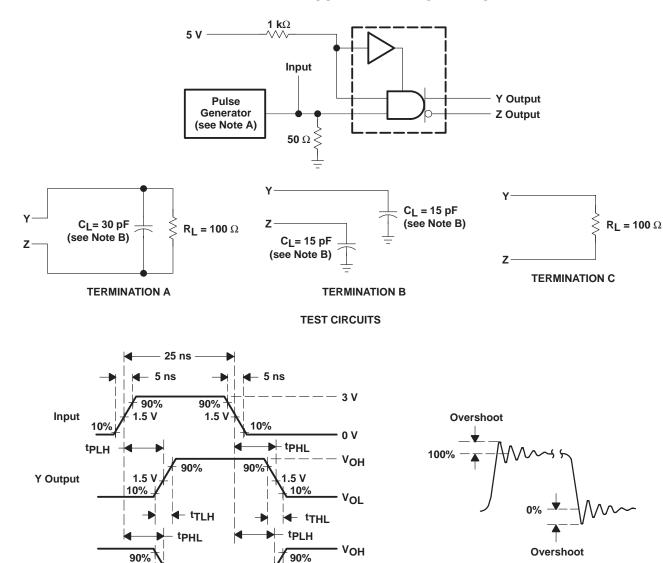


Figure 1. Differential and Common-Mode Output Voltages

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

 v_{OL}

NOTES: A. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, PRR $\leq 10 \text{ MHz}$.

1.5 V

10%

B. C_L includes probe and jig capacitance.

1.5 V

10%

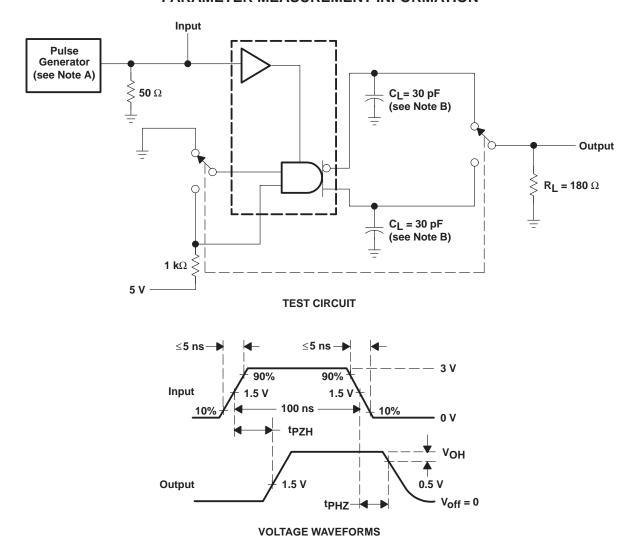
- tTHL

Figure 2. Test Circuits, Voltage Waveforms, and Overshoot Factor



Z Output

PARAMETER MEASUREMENT INFORMATION

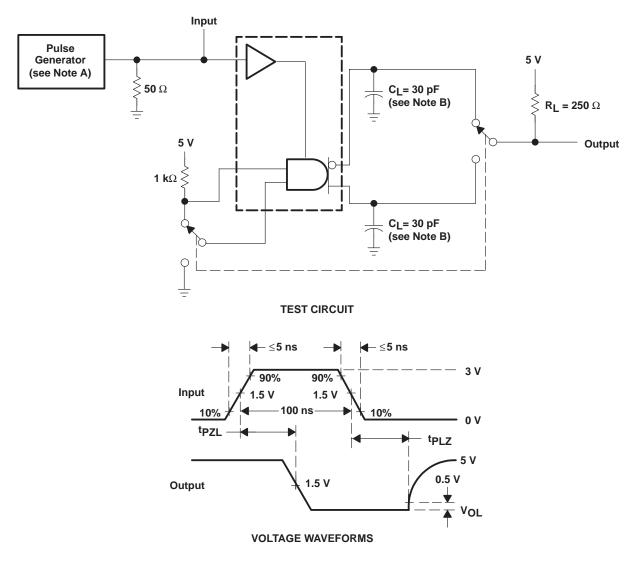


NOTES: A. The pulse generator has the following characteristics: Z_O = 50 Ω , PRR \leq 500 kHz.

B. C_L includes probe and jig capacitance.

Figure 3. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



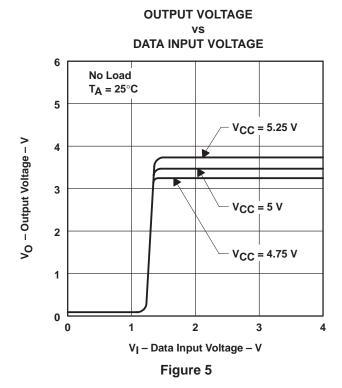
NOTES: A. The pulse generator has the following characteristics: Z_O = 50 Ω , PRR \leq 500 kHz.

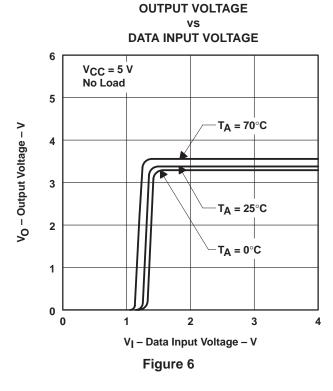
B. C_L includes probe and jig capacitance.

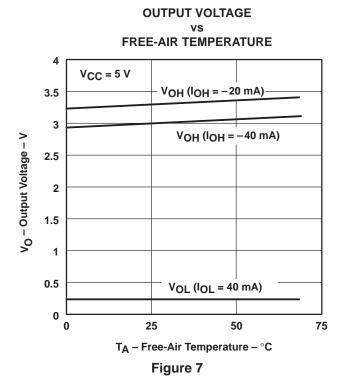
Figure 4. Test Circuit and Voltage Waveform

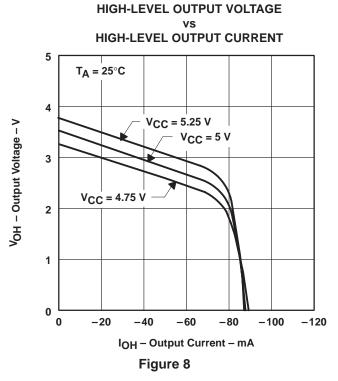


TYPICAL CHARACTERISTICS

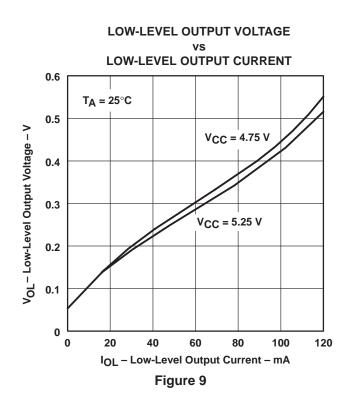


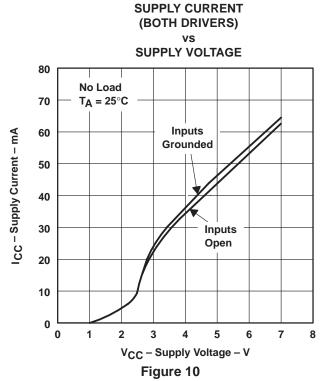


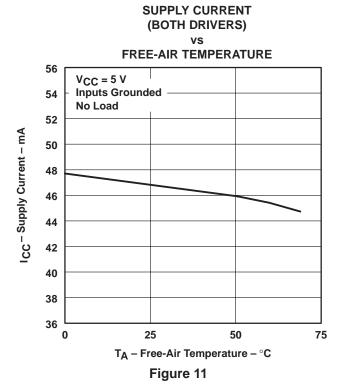


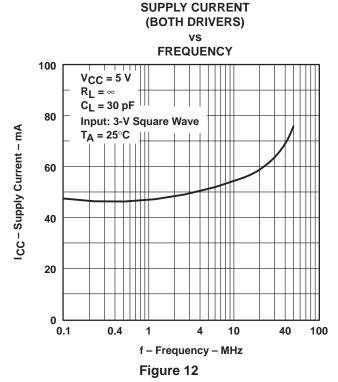


TYPICAL CHARACTERISTICS









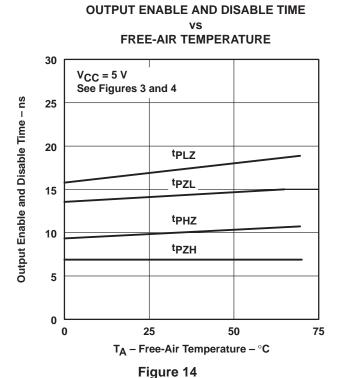


TYPICAL CHARACTERISTICS

FROM DATA INPUTS FREE-AIR TEMPERATURE 20 Propagtion Delay Time From Data Inputs - ns 18 **tPLH** 16 14 **tPHL** 12 10 8 6 4 V_{CC} = 5 V C_L = 30 pF 2 $R_L = 100 \Omega$ 0 75 0 T_A – Free-Air Temperature – $^{\circ}C$

Figure 13

PROPAGATION DELAY TIME



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75159D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75159NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75159NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75159NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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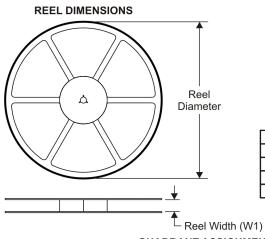


PACKAGE OPTION ADDENDUM

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to Customer on an annual basis.	



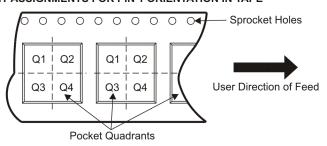
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

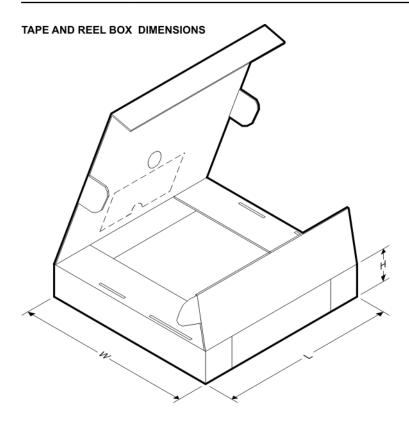
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75159DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75159NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
S	N75159DR	SOIC	D	14	2500	346.0	346.0	33.0
SI	N75159NSR	SO	NS	14	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



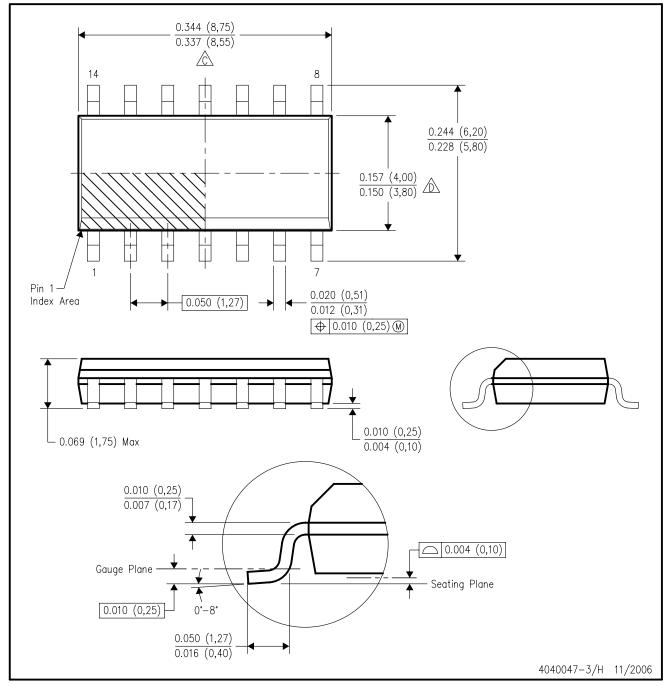
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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